

CLAIMS

1. A mold fabricating method, comprising:
 - providing a base plate;
 - forming recesses in the base plate using a series of photo mask processes.
2. The method as claimed in claim 1, wherein each photo mask process formed recesses.
3. The method as claimed in claim 2, wherein each photo mask process comprises following steps:
 - covering a resist film on the base plate;
 - forming a mask;
 - forming pattern in the resist film by radiation exposure through the mask;
 - etching the base plate by chemical method to get recesses;
 - cleaning the remnant resist film and other foreign particles.
4. The method as claimed in claim 3, wherein an aligning step is performed between two photo mask step.
5. The method as claimed in claim 4, wherein the base plate is made of nickel or nickel alloy.
6. The method as claimed in claim 5, wherein the resist film comprises a resist and an organic polymer.
7. The method as claimed in claim 6, wherein the resist film adopts positive acting resist.
8. The method as claimed in claim 6, wherein the resist film adopts negative-acting resist.
9. The method as claimed in claim 1, wherein each photo mask process

formed narrower and deeper recesses in the same position of the former photo mask process in the base plate.

10. The method as claimed in claim 9, wherein each photo mask process comprises following steps:

- covering a resist film on the base plate;

- forming a mask;

- forming pattern in the resist film by radiation exposure through the mask;

- etching the base plate by chemical method to get recesses;

- cleaning the remnant resist film and other foreign particles.

11. The method as claimed in claim 10, wherein an aligning step is performed between two photo mask step.

12. The method as claimed in claim 11, wherein the base plate is made of nickel or nickel alloy.

13. The method as claimed in claim 12, wherein the resist film comprises a resist and an organic polymer.

14. The method as claimed in claim 13, wherein the resist film adopts positive acting resist.

15. The method as claimed in claim 14, wherein the resist film adopts negative-acting resist.